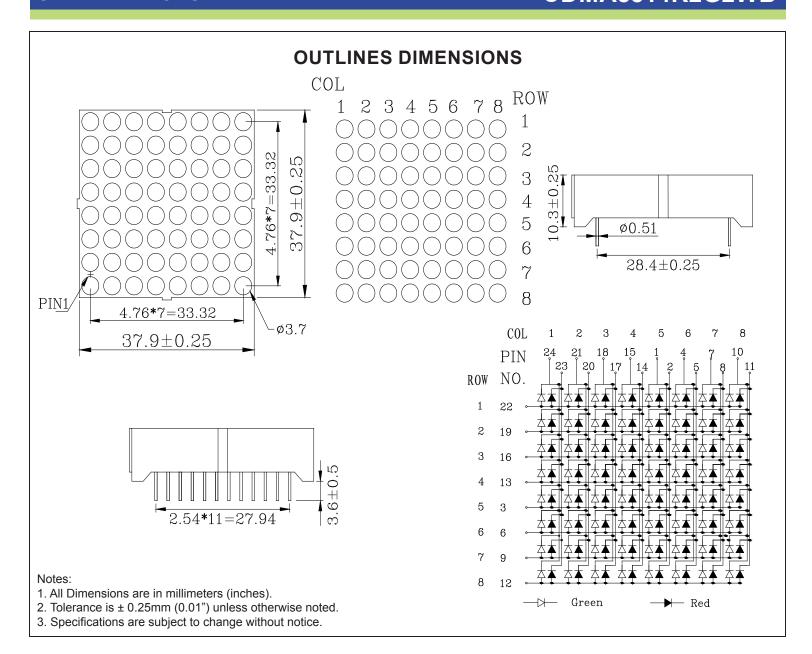


SPECIFICATIONS

CDMA8814R2G2WB



Part Number	Chip Material	Color of Emission	Lens Type	Description	
CDMA8814R2G2WB	InGaAIP	Red	White Segment/	Common Anode	
CDIVIA0014R2G2VVB	InGaAIP	Green	Black Face		





ABSOLUTE MAXIMUM RATINGS - RED (InGaAIP)

 $(TA=25^{\circ}C)$

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	Pb	80	mW	
Pulse Forward Current	lFP	120	mA	
Continuous Forward Current	lF	20	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Тѕтс	-35~+85	°C	
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec				

OPTICAL-ELECTRICAL CHARACTERISTICS - RED (InGaAIP)

(TA=25°C)

Parameter	Symbol	Test Condition	Value			Unit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I⊧ = 10mA	6145	10383	-	ucd
Forward Voltage	VF	I⊧ = 20mA	ı	1.8	2.2	V
Reverse Leakage Current	lR	V _R = 5V	1	ı	20	μΑ
Peak Wavelength	λР	I _F = 20mA	635	ı	650	nm
Dominant Wavelength	λD	I⊧ = 20mA	-	630	-	nm
Spectral Radiation Bandwidth	Δλ	I⊧ = 20mA	-	20	-	nm





ABSOLUTE MAXIMUM RATINGS - GREEN (InGaAIP)

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	Pb	80	mW	
Pulse Forward Current	lFP	120	mA	
Continuous Forward Current	lF	20	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Тѕтс	-35~+85	°C	
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec				

OPTICAL-ELECTRICAL CHARACTERISTICS - GREEN (InGaAIP)

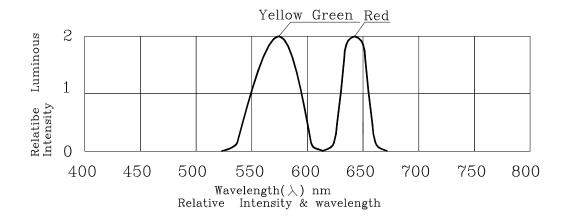
 $(TA=25^{\circ}C)$

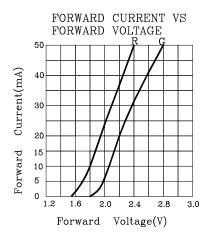
Doromotor	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I⊧ = 10mA	6145	10383	ı	ucd
Forward Voltage	VF	I _F = 20mA	ı	2.1	2.5	V
Reverse Leakage Current	lR	V _R = 5V	-	-	20	μΑ
Peak Wavelength	λР	I _F = 20mA	568	ı	575	nm
Dominant Wavelength	λD	I _F = 20mA	-	573	-	nm
Spectral Radiation Bandwidth	Δλ	I⊧ = 20mA	-	20	-	nm

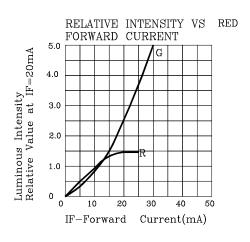


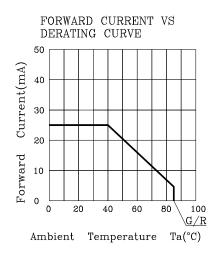


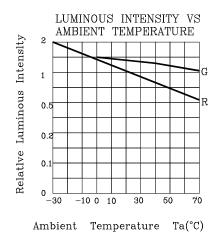
OPTICAL CHARACTERISTIC CURVES















RECOMMENDED SOLDERING PROFILE

The recommended conditions for soldering are as follows. Because the component is made with epoxy resin, the units are susceptible to heat. Therefore, the preheating and soldering temperatures should be kept as low as possible to avoid damage.

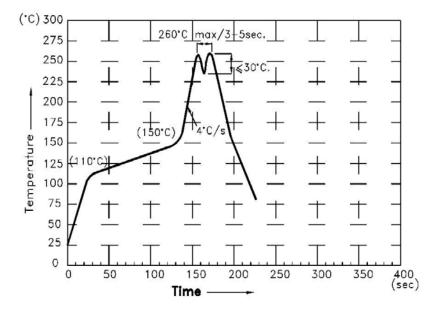
1. Manual Soldering Conditions(with 1.5mm Iron tip)

Iron Tip Temperature: 350°C Max, Time: 3s Max

Position: The iron should be situated at least 2mm away from the root of the leads.

2. Through the Wave Soldering Conditions

Wave Soldering Profile For Lead-free Through-hole LED



3 . Soldering General Notes:

- a. Toplight recommend manual soldering to be used only for repair and rework purposes. The soldering iron should not exceed 30W in power. The tip of the soldering iron should not touch the reflector case to avoid heat-damage.
- b. Maintain the pre-heat and peak temperatures with dip units as low as possible and the times as short as is feasible, since the products are susceptible to heat during flow soldering.
- c. After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
- d. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Toplight for compatibility.

